Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM	IPC ASSOCIATION ELECTRONICS	Material Comp © Copyright 2005. I international and Par	osition De IPC, Bannockl n-American c	claration burn, Illinois. A opyright conve	all rights reserved untions.	under both	This docume level parts, the	ent is a declaration	ation of encomp	the substances passes all lowe	within the r level mat	manufactur terials for wl	er listed ite hich the ma	m. Note nufactu	e: if the item is an arer has engineering	assembly with long responsibility.
Company name* Company unique ID Unique ID Authority Response Date* 2025-06-08 Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards	752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type					e *							nation		
Contact Name Title - Contact Phone - Contact* Phone - Contact* Product-Env-Stewards Product-Env-Stewar	upplier	Information														
Title - Contact Phone - Contact* Phone - Contact* Product-Env-Stewards Product-Env-	Company 1	name*		Company un	ique ID		ī	Unique ID Au	thority				Response	Date*		
Product-Env-Stewards Authorized Representative* Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester Item Number Mfr Item Number Mfr Item Name Representative Broduct-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Beffective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA O C 30 Seconds 3	nsemi												2025-06-0	8		
Authorized Representative* Product Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy Product Enviro Compliance NA Email - Representative* Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM 16949.998 mg Manufacturing Proccess Information Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 Seconds 3	ontact Na	ame		Title - Conta	ct]	Phone - Cont	act*				Email - C	ontact*	*	
Product-Env-Stewards Product-Env-Stewards	Product-E	Env-Stewards		Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM GBPC2502 BR GBPC GPPN 25A 200V 2025-06-08 TSCBE 16949.998 mg Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3	Authorized Representative* Title -				Citle - Representative			Phone - Representative*				Email - Representative*				
GBPC2502 BR GBPC GPPN 25A 200V 2025-06-08 TSCBE 16949.998 mg	Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3		Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Da	te Vei	rsion	Manufactu	ring Site	W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3			GBPC25	502	BR GBPC GPPN	I 25A 200V		2025-06-08		,	ГЅСВЕ		16	5949.99	8 mg	Each
Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3	Ianufac	cturing Proccess Informa	tion												1	
		Terminal Plating / Grid Array Ma	aterial	Γerminal Base Alloy J-		J-STD-020 MS	SL Rating	Peak Pro	Peak Process Body Temperatur		nre Max Time at Peak Temper		Temperatur	re Number of Reflow Cycles		Cycles
			PdAu) (no	CU Alloy		NA		0		С	30		seconds	3		
Comments	omments															

RoHS Material Composition Declaration			Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).		
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components. Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated diphen s of an applicable quantity limit, please indications that it gathered the information it provious. Supplier acknowledges that Company will ave relied on information provided by others, Supplier agrees that, at a minimum of and the Supplier enter into a written agreent assource of the Supplier's liability and the Core	EU 2011/65/EU and implemented by the laws of the nyl ethers (each a "RoHS restricted substance") in ecate below which, if any, RoHS exemption you belides in this form using appropriate methods to ensuil rely on this certification in determining the compin completing this form, and that Supplier may not man, its suppliers have provided certifications regarding ment with respect to the identified part, the terms anomany's remedies for issues that arise regarding in licable to such part shall apply.	xcess of the applicable quantity limit identified ab eve may apply. If the part is an assembly with low e its accuracy and that such information is true and iance of its products with European Union membe have independently verified such information. Ho g their contributions to the part, and those certificat conditions of that agreement, including any warra	ove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting tempe Exemption: 7c-I Electrical and electronic c	erature type solders (i.e. lead based solder omponents containing lead in a glass or co	r alloys containing 85% by weight or more lead) ceramic other than dielectric ceramic in capacito	rs, e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.
Exemption List Version	EL-2011/534/EU			
Declaration Signature				
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature R		,		

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	2949.3	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		589.8748	mg
			Supplier	Silica (SiO2)	14464-46-1		2064.5603	mg
			Supplier	Phosphorus (P)	7723-14-0		58.9152	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		235.9497	mg
Die	33.561	mg	Supplier	Silicon (Si)	7440-21-3		30.2049	mg
			В	Nickel (Ni)	7440-02-0		0.2181	mg
			Supplier	Gold (Au)	7440-57-5		0.0503	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	3.0876	mg
Die Attach Solder	18.1365	mg	Supplier	Silver (Ag)	7440-22-4		0.4534	mg
			A	Lead (Pb)	7439-92-1	7a	16.7763	mg
			Supplier	Tin (Sn)	7440-31-5		0.9068	mg
Die Attach Solder - Solder Wafer	82.8855	mg	Supplier	Silver (Ag)	7440-22-4		2.0721	mg
			A	Lead (Pb)	7439-92-1		76.6691	mg
			Supplier	Tin (Sn)	7440-31-5		4.1443	mg
Heat Sink	3803.24	mg	Supplier	Aluminum (Al)	7429-90-5		3803.24	mg
Lead Frame	1220.4	mg	Supplier	Iron (Fe)	7439-89-6		0.9763	mg
			Supplier	Copper (Cu)	7440-50-8		1219.1797	mg
			Supplier	Phosphorus (P)	7723-14-0		0.244	mg
Marking Ink	0.5085	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.0254	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.0254	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.0509	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.3305	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0763	mg
Mold Compound-White	6552.36	mg		Polymer Resin	proprietary data		1092.2784	mg
			Supplier	1,2-Bis(pentabromophenyl) ethane	84852-53-9		382.0026	mg
			Supplier	Brominated epoxy resin	Proprietary Data		1419.8964	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		218.1936	mg
			Supplier	Carbon Black (C)	1333-86-4		54.3846	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		655.236	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2730.3682	mg
Plating-2	14.916	mg	В	Nickel (Ni)	7440-02-0		14.916	mg
Terminal	2274.69	mg	Supplier	Iron (Fe)	7439-89-6		2.7296	mg

	Supplier	Copper (Cu)	7440-50-8	2270.9822	mg
	Supplier	Phosphorus (P)	7723-14-0	0.9781	mg